

	Class	Subclass	
ISSUE CLASSIFICATION			

OST O.I.P.E.

PATENT DATE

SCANNED *KC00* Q.A.

APPLICATION NO. 09/996118	CONT/PRIOR	CLASS 257	SUBCLASS 687	ART UNIT 2814	EXAMINER S. RAO
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APPLICANTS

Chuan-cheng Cheng
Sethuraman Lakshminarayanan
Peter Wright
Hong Ying

3.11.1

Low resistance metal interconnect lines and a process for fabricating them

PTO-2040
12/89

ISSUING CLASSIFICATION												
ORIGINAL				CROSS REFERENCE(S)								
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)							
INTERNATIONAL CLASSIFICATION												

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)		NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____ _____	_____ (Primary Examiner) (Date)		ISSUE FEE	
			Amount Due	Date Paid
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) (Date)		ISSUE BATCH NUMBER	

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